

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 7 and add new claim 18 as follows:

LISTING OF CLAIMS:

1. (Withdrawn) A holding jig comprising:

an elastic material wherein at least the surface thereof is adhesive and conductive, and wherein an electronic part or component constituting the electronic part is holdable by the adhesive strength of the surface of the elastic material.
2. (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made to be conductive by adding conductive material to the elastic material.
3. (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made by conductive by installing a wiring using conductive material on the surface of the elastic material.
4. (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made to be conductive by installing a wiring using conductive material inside the elastic material, the wiring being exposed on the surface of the elastic material.

5. (Canceled)

6. (Canceled)

7. (Currently Amended) A method of manufacturing electronic parts,
comprising the steps of:

~~holding~~ providing a holding jig made of an elastic material, wherein at least one surface of said elastic material is adhesive;

mounting a substrate on ~~a surface of a~~ the holding jig ~~made of an elastic material, in which at least the surface of said elastic material is adhesive,~~ by ~~[[the]]~~ an adhesive strength of said surface of the elastic material;

mounting an element onto said substrate and electrically connecting ~~[[an]]~~ the element ~~[[on]]~~ to said substrate while the substrate is held on the surface of the elastic material; and

applying ultrasonic waves to ~~[[the]]~~ a bonding portion at which the electric connection is performed.

8. (Canceled)

9. (Original) The method of manufacturing electronic parts according to claim 7, wherein the hardness of the elastic material is a rubber hardness degree of at least A30.

10. (Previously Presented) The method of manufacturing electronic parts according to claim 9, wherein the step of holding said substrate includes using the holding jig which comprises heat-resistant material having a heat-resistance temperature of about 250°C.

11. (Previously Presented) The method of manufacturing electronic parts according to claim 9, wherein the step of holding said substrate includes using the holding jig which includes a laminate structure of a hard plate and the elastic material.

12. (Previously Presented) The method of manufacturing electronic parts according to claim 9, wherein the elastic material comprises silicone resin.

13. (Previously Presented) The method of manufacturing electronic parts according to claim 9, wherein the mounting process includes a wire bonding process.

14. (Previously Presented) The method of manufacturing electronic parts according to claim 9, wherein the mounting process includes a bump bonding process.

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (New) The method of manufacturing electronic parts according to claim 7, wherein ultrasonic waves are applied while the substrate is held on the surface of the elastic material.